

RCJ120N25 Nch 250V 12A Power MOSFET

V _{DSS}	250V
R _{DS(on)} (Max.)	$235 m\Omega$
I _D	12A
P _D	107W

Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating ; RoHS compliant
- 6) 100% Avalanche tested

Application

Switching Power Supply

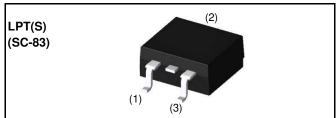
Automotive Motor Drive

Automotive Solenoid Drive

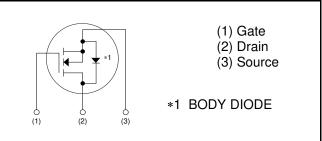
●Absolute maximum ratings(T_a = 25°C)

Value Parameter Symbol Unit V_{DSS} 250 V Drain - Source voltage I_D^{*1} $T_c = 25^{\circ}C$ ±12 А Continuous drain current I_D^{*1} $T_{c} = 100^{\circ}C$ ±6.5 А *2 Pulsed drain current I_{D,pulse} ±48 А $\mathsf{V}_{\mathsf{GSS}}$ V Gate - Source voltage ±30 *3 Avalanche energy, single pulse E_{AS} 10.5 mJ *3 Avalanche current 6.0 А I_{AR} $T_c = 25^{\circ}C$ P_{D} 107 W Power dissipation $T_a = 25^{\circ}C^{*4}$ P_{D} 1.56 W Ti 150 °C Junction temperature T_{stg} -55 to +150 °C Range of storage temperature

Outline



Inner circuit



Packaging specifications

Туре	Packaging	Taping
	Reel size (mm)	330
	Tape width (mm)	24
	Quantity (pcs)	1,000
	Taping code	TL
	Marking	RCJ120N25

•Thermal resistance

Parameter	Symbol	Values			Unit
Farameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	1.16	°C/W
Thermal resistance, junction - ambient *4	R_{thJA}	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	°C

•Electrical characteristics($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 1mA$	250	-	-	V
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 250V, V_{GS} = 0V$ $T_j = 25^{\circ}C$	-	-	10	μA
Gate - Source leakage current	I _{GSS}	$V_{GS}=\pm 30V,\ V_{DS}=0V$	-	-	±100	nA
Gate threshold voltage	$V_{GS\ (th)}$	$V_{DS} = 10V, I_{D} = 1mA$	3.0	-	5.0	V
		$V_{GS} = 10V, I_D = 6.0A$	-	180	235	
Static drain - source on - state resistance	$R_{DS(on)}$ *5	$V_{GS} = 10V, I_D = 6.0A$ $T_j = 125^{\circ}C$	-	340	480	mΩ
Forward transfer admittance	9 _{fs}	$V_{DS} = 10V, I_{D} = 6.0A$	3.25	6.50	-	S

•Electrical characteristics($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	1800	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	100	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	60	-	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 125V, V_{GS} = 10V$	-	33	-	
Rise time	t _r *5	I _D = 6.0A	-	65	-	20
Turn - off delay time	t _{d(off)} *5	R _L = 12Ω	-	45	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	20	-	

•Gate Charge characteristics($T_a = 25^{\circ}C$)

Parameter	Symbol	Conditions	Values			Unit
Farameter			Min.	Тур.	Max.	Unit
Total gate charge	Q_g^{*5}	$V_{DD} \simeq 125V$	-	35	-	
Gate - Source charge	${\sf Q_{gs}}^{*5}$	I _D = 12A	-	15	-	nC
Gate - Drain charge	${\sf Q}_{\sf gd}$ *5	$V_{GS} = 10V$	-	12	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 125V, \ I_D = 12A$	-	7.6	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous source current	I_{S}^{*1}	T _c = 25°C	-	-	12	А
Pulsed source current	I_{SM} *2	$r_{c} = 25.0$	-	-	48	А
Forward voltage	V_{SD} *5	$V_{GS} = 0V, I_{S} = 12A$	-	-	1.5	V
Reverse recovery time	t _{rr} *5	I _S = 6.0A	-	105	-	ns
Reverse recovery charge	Q _{rr} ^{*5}	di/dt = 100A/µs	-	410	-	nC

*1 Limited only by maximum temperature allowed.

*2 Pw \leq 10 $\mu s,$ Duty cycle \leq 1%

*3 L \simeq 500 μ H, V_{DD} = 50V, Rg = 25 Ω , starting T_j = 25°C

*4 Mounted on a epoxy PCB FR4 (25mm × 27mm × 0.8mm)

*5 Pulsed

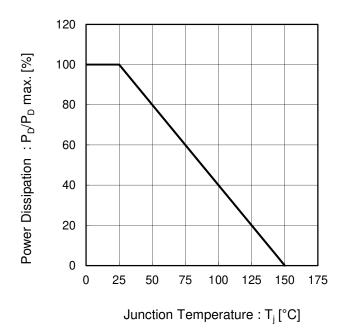
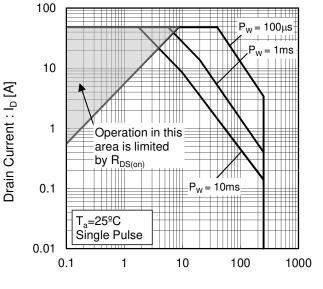


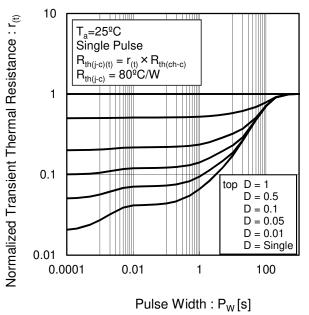
Fig.1 Power Dissipation Derating Curve





Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



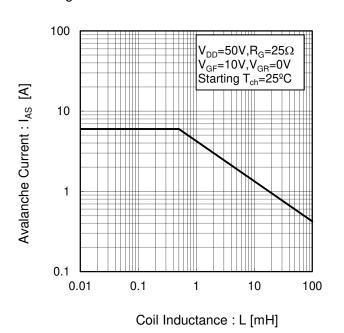
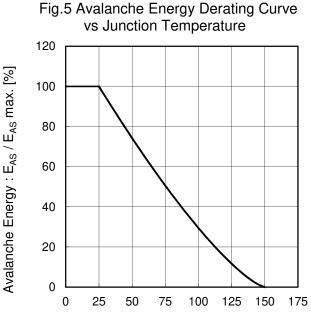
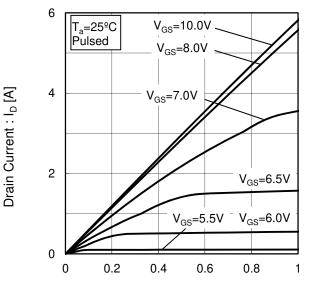


Fig.4 Avalanche Current vs Inductive Load

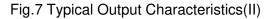


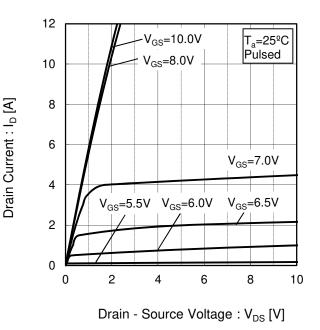
Junction Temperature : T_i [°C]

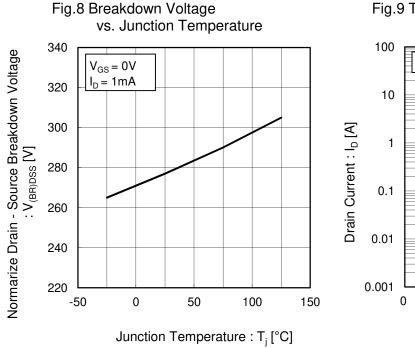
Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]







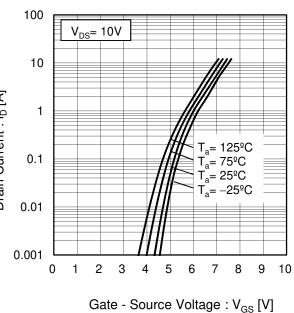
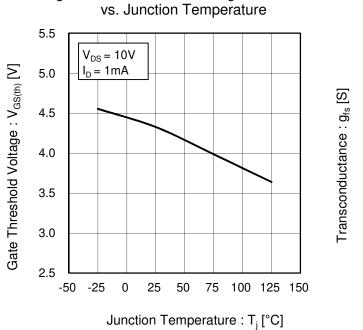


Fig.9 Typical Transfer Characteristics



Fig.11 Transconductance vs. Drain Current



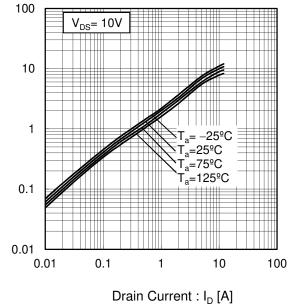
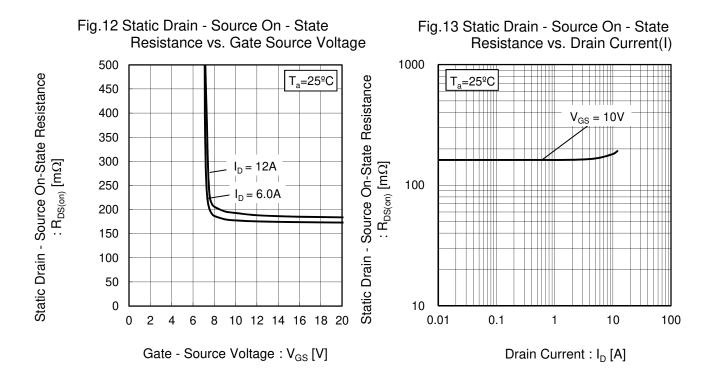
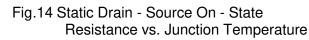
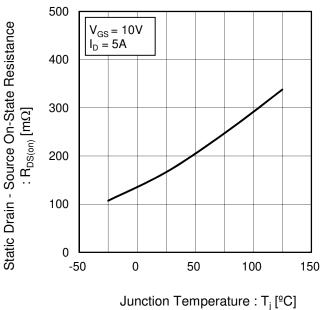
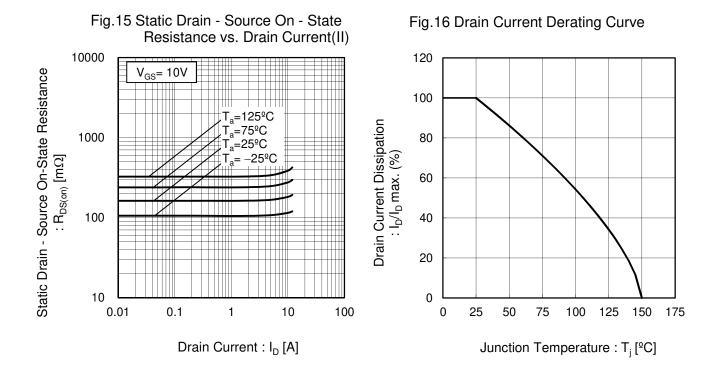


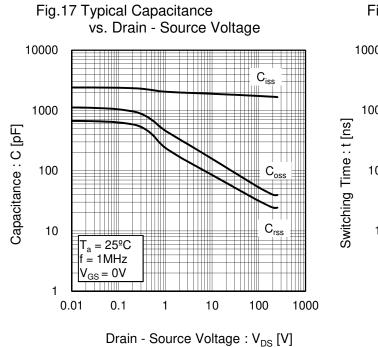
Fig.10 Gate Threshold Voltage











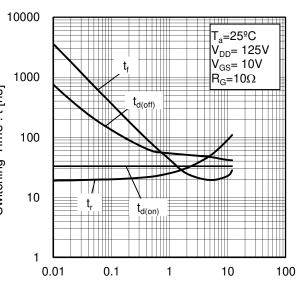
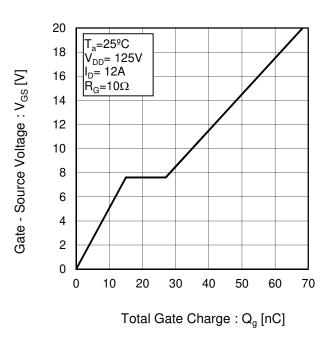


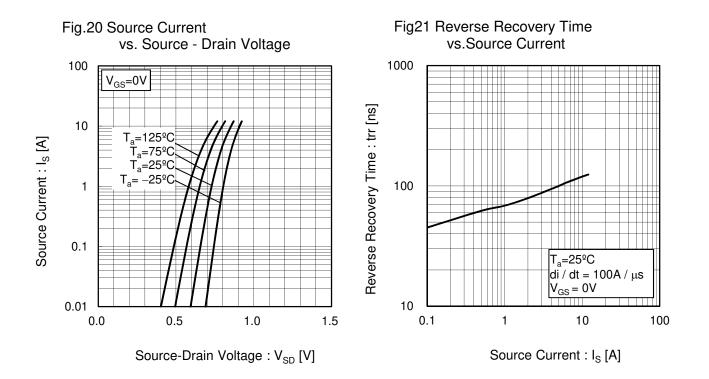
Fig.18 Switching Characteristics

Drain Current : I_D [A]

Fig.19 Dynamic Input Characteristics



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Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

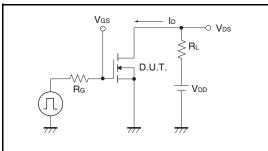


Fig.2-1 Gate Charge Measurement Circuit

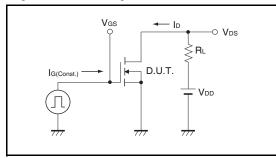


Fig.3-1 Avalanche Measurement Circuit

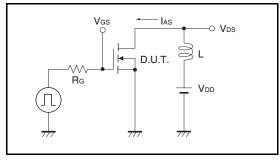


Fig.1-2 Switching Waveforms

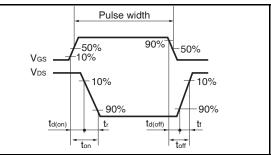


Fig.2-2 Gate Charge Waveform

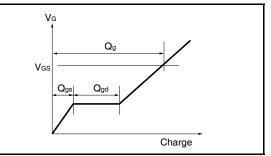
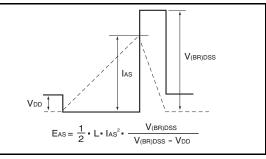
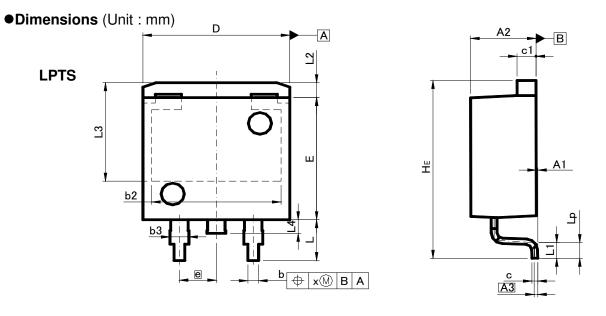
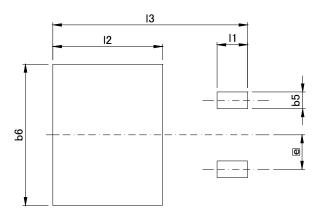


Fig.3-2 Avalanche Waveform







Patterm of terminal position areas

DIM	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
A1	0.00	0.30	0	0.012	
A2	4.30	4.70	0.169	0.185	
A3	0.	25	0.	01	
b	0.68	0.98	0.027	0.039	
b2	8.	90	0.	35	
b3	1.14	1.44	0.045	0.057	
с	0.30	0.60	0.012	0.024	
c1	1.10	1.50	0.043	0.059	
D	9.80	10.40	0.386	0.409	
E	8.80	9.20	0.346	0.362	
е	2.	54	0.10		
HE	12.80	13.40	0.504	0.528	
L	2.70	3.30	0.106	0.13	
L1	0.90	1.50	0.035	0.059	
L2	1.	10	0.0)43	
L3	7.25		0.2	85	
L4	1.00		0.0)39	
Lp	0.90	1.50	0.035	0.059	
х	-	0.25	-	0.01	

DIM	MILIM	ETERS	RS INCHES		
DIN	MIN	MAX	MIN	MAX	
b5	-	1.23	-	0.049	
b6	-	10.40	-	0.409	
1	-	2.10	-	0.083	
12	-	7.55	-	0.297	
13	-	13.40	-	0.528	

Dimension in mm/inches

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(Note1) Medical Equipment Classification of the S	pecific Applications
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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSIII	CLASSⅢ	CLASSI

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 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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